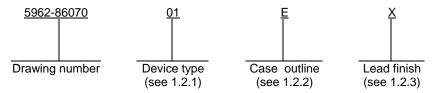
LTR						DESCF	RIPTIO	N					DATE (YR-MO-DA)			APPROVED		,		
А	I I <sub>IL</sub> c	Change vendor part number from 54F148/B2C to 54F148/B2A. Table I I <sub>IL</sub> column delete IE and substitute EI. Table I t <sub>PHL6</sub> maximum limits column delete 11 and substitute 13. Add figure 4 to document. Editorial changes throughoutljs								88-12-13		M. A. Frye								
В	Revi	se for	"QD"	certific	ation.	New	boilerp	olate.	-ljs					99-1	1-08		Rayı	mond	Monn	in
С	Upda	Update to current requirements. Editorial changes th			ges thi	rougho	ut g	ар		06-0	)1-04		Ray	mond	Monn	in				
	st page o	of this d	rawing	ı has be	een rep	placed.			T	<u> </u>			<u> </u>		T	<u> </u>		1		
REV	st page o	of this d	rawing	has be	een rep	placed.														
REV SHEET	st page o	of this d	rawing	ı has be	een rep	placed.														
REV SHEET REV	st page o	of this d	rawing	ı has be	een rep	placed.														
REV SHEET REV SHEET		of this d	rawing	has be		placed.	C	С	C	С	С	С	С	С	С	C				
REV SHEET REV SHEET		of this d	rawing		,	placed.	C 1	C 2	C 3	C 4	C 5	C 6	C 7	C 8	C 9	C 10				
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A			rawing	REV SHE PRE	EET PARE arry T	ED BY	1				5	6 EFEN	7 SE SI	8 JPPL	9 .Y <b>CE</b>	10			US	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A	INDAF	RD	rawing	REV SHE PRE L	EPARE arry T	ED BY Gaud	1 der				5	6 EFEN	7 SE SI	8 UPPLIBUS,	9 .Y CE	10	218-39		US	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A  STA MICRO DRA  THIS DRAWII FOR L DEPA	NDAF OCIRC AWING NG IS A JSE BY A	RD CUIT G VAILAE	BLE	REV SHE PRE L	EPARE arry T	ED BY	der			MIC SCI	DIE CROCHOTT	EFEN CC	SE SI DLUM http	8 UPPL IBUS, :://ww	9 Y CE, OHIO	10 NTER O 432	218-39 a.mil LAR,	990 ———	'ANC	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A  STA MICRO DRA  THIS DRAWII FOR L	NDAF OCIRC AWING NG IS A JSE BY A RTMEN NCIES C	RD CUIT G VAILAE ALL TS DF THE	BLE	REV SHE PRE L	PROVE	ED BY C Gaud D BY Onnin ED BY Onnin	der	2	3	MIC SCI	DIE CROCHOTT	EFEN CC	SE SI DLUM http	8 UPPL IBUS, :://ww	9 Y CE, OHIO	NTER O 432	218-39 a.mil LAR,	990 ———	'ANC	
STA MICRO DRA THIS DRAWII FOR L DEPA AND AGE DEPARTME	NDAF OCIRC AWING NG IS A JSE BY A RTMEN NCIES C	RD CUIT G VAILAE ALL TS DF THE	BLE	REV SHE PRE L	ECKEL Ray Mo	ED BY C Gaud D BY onnin ED BY el A. Fr 87-1	der rye ROVA	2	3	MIC SCI MO	DIE CROCHOTT	EFEN CO CIRCI TKY T	SE SI DLUM http	BUS, DIGIT B-BIT ICON	9 Y CE, OHIO	NTER D 432 ccc.dla	218-39 a.mil LAR,	ADV MPA	ANC RAT	

**REVISIONS** 

# 1. SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.
  - 1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 Device type(s). The device type(s) identify the circuit function as follows:

Device type	Generic number	<u>Circuit function</u>
01	54F148	8-line to 3-line priority encoder

1.2.2 <u>Case outline(s)</u>. The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
E	GDIP1T-16 or CDIP2-T16	16	dual-in-line
F	GDFP2-F16 or GDFP3-F16	16	flat package
2	CQCC1-N20	20	square chip carrier

- 1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.
- 1.3 Absolute maximum ratings.

Supply voltage range	-0.5 V dc minimum to +7.0 V dc maximum
Input voltage range	-1.5 V at -18 mA to +7.0 V dc
Storage temperature range	-65°C to +150°C
Maximum power dissipation (P <sub>D</sub> ) 1/	193 mW
Lead temperature (soldering, 10 seconds)	+300°C
Thermal resistance, junction-to-case ( $\theta_{JC}$ )	See MIL-STD-1835
Junction temperature(T <sub>J</sub> )	+175°C

1.4 Recommended operating conditions.

Supply voltage range (V <sub>CC</sub> )	4.5 V minimum to 5.5 V maximum
Minimum high level input voltage (V <sub>IH</sub> )	2.0 V dc
Maximum low level input voltage (V <sub>IL</sub> )	0.8 V dc
Case operating temperature (T <sub>C</sub> )	-55°C to +125°C

<sup>1/</sup> Maximum power dissipation is defined as V<sub>CC</sub> x I<sub>CC</sub>, and must withstand the added P<sub>D</sub> due to short circuit test, e.g. I<sub>OS</sub>

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-86070
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL C	SHEET 2

## 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

## DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

#### DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

## DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <a href="http://assist.daps.dla.mil;quicksearch">http://assist.daps.dla.mil;quicksearch</a>/ or <a href="www.dodssp.daps.mil">www.dodssp.daps.mil</a> or from the Standardization Document Order Desk. 700 Robbins Avenue, Building 4D. Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

## 3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used. This drawing has been modified to allow the manufacturer to use the alternate die/fabrication requirements of paragraph A.3.2.2 of MIL-PRF-38535 or other alternative approved by the qualifying activity.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.
  - 3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.2 herein.
  - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.
  - 3.2.3 Truth table. The truth table shall be as specified on figure 2.
  - 3.2.4 Logic diagram. The logic diagram shall be as specified on figure 3.
  - 3.2.5 Test circuit and switching waveforms. The test circuit and switching waveforms shall be as specified on figure 4.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-86070
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL C	SHEET 3

- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.
- 3.5.1 <u>Certification/compliance mark</u>. A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used. For product built in accordance with A.3.2.2 of MIL-PRF-38535, or as modified in the manufacturer's QM plan, the "QD" certification mark shall be used in place of the "Q" or "QML" certification mark.
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
  - 3.8 Notification of change. Notification of change to DSCC-VA shall be required for any change that affects this drawing.
- 3.9 <u>Verification and review</u>. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

#### 4. VERIFICATION

- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test, method 1015 of MIL-STD-883.
    - (1) Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
    - (2)  $T_A = +125^{\circ}C$ , minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-86070
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL C	SHEET 4

TABLE I. <u>Electrical performance characteristics</u>.

Test	Symbol				Limits		Unit
					Min	Max	
High level output voltage	V <sub>OH</sub>	$V_{CC} = 4.5 \text{ V},$ $I_{OH} = -1 \text{ mA},$	$V_{IL} = 0.8 \text{ V}$ $V_{IH} = 2.0 \text{ V}$	1, 2, 3	2.5		V
Low level output voltage	V <sub>OL</sub>	$V_{CC} = 4.5 \text{ V},$ $I_{OL} = 20 \text{ mA},$	$V_{IL} = 0.8 \text{ V}$ $V_{IH} = 2.0 \text{ V}$	1, 2, 3		0.5	V
Input clamp voltage	V <sub>IC</sub>	$V_{CC} = 4.5 \text{ V},$	$I_{IN} = -18 \text{ mA}$	1, 2, 3		-1.2	V
High level input current	I <sub>IH1</sub>	$V_{CC} = 5.5 \text{ V},$	$V_{IN} = 7.0 \text{ V}$	1, 2, 3		100	μΑ
	I <sub>IH2</sub>	$V_{CC} = 5.5 \text{ V},$	V <sub>IN</sub> = 2.7 V	1, 2, 3		20	μΑ
Low level input current	I <sub>IL</sub>	$V_{CC} = 5.5 \text{ V}$	lo, El	1, 2, 3		-0.6	mA
		V <sub>IN</sub> = 0.5 V	Ī <sub>1</sub> , Ī <sub>7</sub>	1, 2, 3		-1.2	mA
Short circuit output current	Ios	$V_{CC} = 4.5 \text{ V},$	V <sub>OUT</sub> = 0.0 V <u>1</u> /	1, 2, 3	-60	-150	mA
Supply current	I <sub>CC</sub>	V <sub>CC</sub> = 5.5 V		1, 2, 3		35	mA
Functional tests		See 4.3.1c		7, 8			
Propagation delay time,	t <sub>PLH1</sub>	V <sub>CC</sub> = 5.0 V		9		9	ns
$\overline{I}_n$ to $\overline{A}_n$		$R_L = 500\Omega$		10, 11		12	
	t <sub>PHL1</sub>	$C_L = 50 pF$		9		11	
				10, 11		15	
Propagation delay time,	t <sub>PLH2</sub>			9		7	ns
Ī₁ to ĒO				10, 11		9	
	t <sub>PHL2</sub>			9		8	
				10, 11		11	
Propagation delay time,	t <sub>PLH3</sub>			9		11	ns
I <sub>n</sub> to GS				10, 11		15	
	t <sub>PHL3</sub>			9		11	
				10, 11		15	
Propagation delay time,	t <sub>PLH4</sub>			9		9	ns
$\overline{EI}$ to $\overline{A}_{n}$				10, 11		12	
	t <sub>PHL4</sub>			9		8	
Description delevations				10, 11		11	
Propagation delay time, El to GS	t <sub>PLH5</sub>			9		7	ns
EI 10 GS				10, 11		9	
	t <sub>PHL5</sub>			9 10, 11		11 15	
Propagation delay time,	t <sub>PLH6</sub>			9		7	ns
El to EO	YPLH6			10, 11		9	110
	t <sub>PHL6</sub>			9		11	
	11120			10, 11		13	

<sup>1/</sup> Not more than one output should be shorted at a time, and the duration of the short circuit condition should not exceed 1 second.

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-86070
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL C	SHEET 5

Case	E and F	2
outlines		
Terminal	l ermina	al symbol
number		
1	Ī <sub>4</sub>	NC
2		<u> </u>
3	<u> </u> 6	<u></u>
4	_   <sub>7</sub>	<u></u>
5	EI	_   <sub>7</sub>
6	$\overline{A_2}$	NC
7	$\frac{\overline{A}_2}{\overline{A}_1}$	EI
8	GND	$\overline{A_2}$
9	$\overline{A_0}$	$\overline{A_1}$
10	- lo	GND
11	Īı	NC
12	$\overline{l_2}$	$\overline{A_0}$
13	- I <sub>3</sub>	- lo
14	GS	Īı
15	ΕO	
16	V <sub>CC</sub>	NC
17		Ī <sub>3</sub>
18		GS
19		ĒΟ
20		V <sub>CC</sub>

NC = No connection

FIGURE 1. <u>Terminal connections</u>.

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-86070
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL C	SHEET 6

Inputs						Outputs							
EO	Īo	Īı	_ l <sub>2</sub>	- I <sub>3</sub>	_   <sub>4</sub>	_ l <sub>5</sub>	_     	Ī <sub>7</sub>	GS	$\overline{A_0}$	A <sub>1</sub>	$\overline{A_2}$	ĒΟ
Н	Χ	Х	Х	Χ	Χ	Χ	Χ	Χ	Н	Н	Н	Н	Н
L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L
L	Χ	Χ	Χ	Χ	Χ	Χ	Χ	L	L	L	L	L	Н
L	Χ	Χ	Χ	Χ	Χ	Χ	L	Н	L	Н	L	L	Н
L	Χ	Χ	Χ	Χ	Χ	L	Н	Н	L	L	Н	L	Н
L	Χ	Χ	Χ	Χ	L	Н	Н	Н	L	Н	Н	L	Н
L	Χ	Χ	Χ	L	Н	Н	Н	Н	L	L	L	Н	Н
L	Χ	Χ	L	Н	Н	Н	Н	Н	L	Н	L	Н	Н
L	Χ	L	Н	Н	Н	Н	Н	Н	L	L	Н	Н	Н
L	L	Н	Н	Н	Н	Н	Н	Н	L	Н	Н	Н	Н

H -= High voltage level L = Low voltage level X = Irrelevant

FIGURE 2. Truth table.

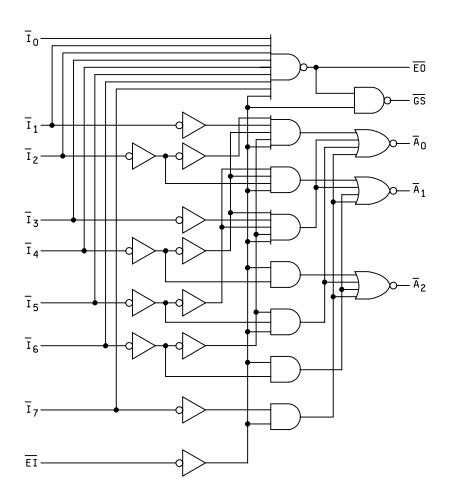
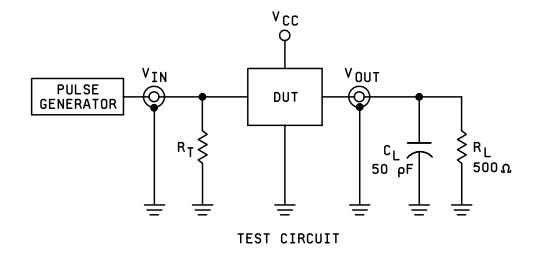
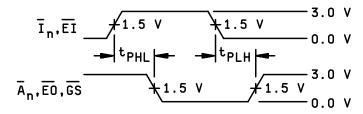


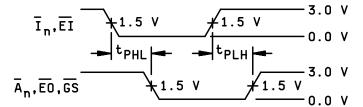
FIGURE 3. Logic diagram.

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-86070
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL C	SHEET <b>7</b>





PROPAGATION DELAY TIMES FOR INVERTING OUTPUTS



PROPAGATION DELAY TIMES FOR NONINVERTING OUTPUTS

## NOTES:

- C<sub>L</sub> includes probe and jig capacitance
   Input pulse requirements: PRR = 1 MHz, t<sub>TLH</sub> = t<sub>THL</sub> = 2.5 ns, duty cycle = 50%.
- 3.  $R_T$  = termination resistance is  $\cong$  to  $Z_{OUT}$  of pulse generator.

FIGURE 4. Test circuit and switching waveforms.

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-86070
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL C	SHEET 8

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9
Group A test requirements (method 5005)	1, 2, 3, 7, 8, 9, 10, 11
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

<sup>\*</sup> PDA applies to subgroup 1.

4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

## 4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 4, 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroups 7 and 8 shall include verification of the truth table.

## 4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
  - (1) Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
  - (2)  $T_A = +125^{\circ}C$ , minimum.
  - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-86070
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL C	SHEET 9

- 5. PACKAGING
- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.
- 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Supply Center Columbus (DSCC) when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0547.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

STANDARD			
MICROCIRCUIT DRAWING			

DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990

SIZE <b>A</b>		5962-86070
	REVISION LEVEL C	SHEET 10

## STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 06-01-04

Approved sources of supply for SMD 5962-86070 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML 38535 during the next revision. MIL-HDBK-103 and QML 38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML 38535.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-8607001EA	0C7V7	54F148/BEA
5962-8607001FA	<u>3</u> /	54F148/BFA
5962-86070012A	<u>3</u> /	54F148/B2A

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- <u>2/</u> <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source.

0C7V7

 Vendor CAGE
 Vendor name

 number
 and address

QP Semiconductor 2945 Oakmead Village Court Santa Clara, CA 95051

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.

# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Encoders, Decoders, Multiplexers & Demultiplexers category:

Click to view products by E2v manufacturer:

Other Similar products are found below:

M38510/01406BEA MC74HC163ADTG 74HC253N HMC854LC5TR NLV74VHC1G01DFT1G NLVHC4851ADTR2G
NLVHCT4851ADTR2G PI3B33X257BE M74HCT4052ADTR2G M74VHC1GT04DFT3G TC74AC138P(F) MC74LVX4051MNTWG
HMC855LC5TR NLV14028BDR2G NLV14051BDR2G NLV74HC238ADTR2G 715428X COMX-CAR-210 5962-8607001EA 59628756601EA MAX3783UCM+D PI5C3253QEX 8CA3052APGGI8 TC74HC4051AF(EL,F) TC74VHC138F(EL,K,F PI3B3251LE
PI5C3309UEX PI5C3251QEX PI3B3251QE 74VHC4052AFT(BJ) PI3PCIE3415AZHEX NLV74HC4851AMNTWG MC74LVX257DG
M74HC151YRM13TR M74HC151YTTR PI5USB31213XEAEX M74HCT4851ADWR2G XD74LS154 AP4373AW5-7-01 QS3VH251QG8
QS4A201QG HCS301T-ISN HCS500-I/SM MC74HC151ADTG TC4066BP(N,F) 74ACT11139PWR HMC728LC3CTR 74VHC238FT(BJ)
74VHC4066AFT(BJ) 74VHCT138AFT(BJ)